



SamHop Microelectronics Corp.

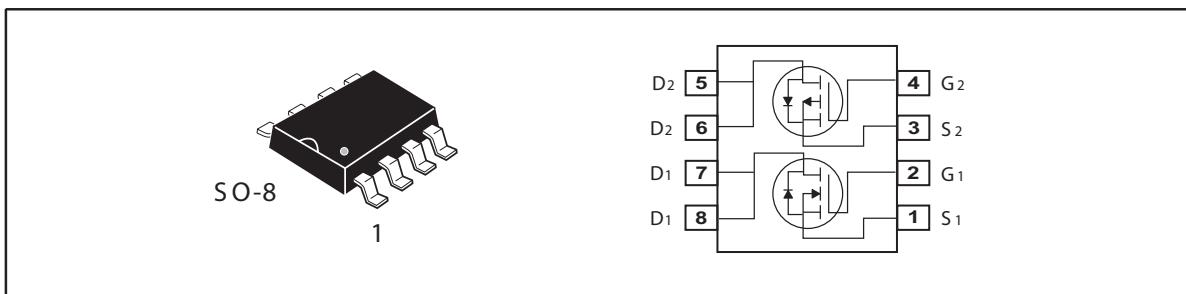
# STM8300

Ver 1.0

## Dual Enhancement Mode Field Effect Transistor ( N and P Channel )

PRODUCT SUMMARY (N-Channel)		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DSON</sub> (mΩ) Max
30V	5.3A	46 @ V <sub>GS</sub> =10V
		65 @ V <sub>GS</sub> =4.5V

PRODUCT SUMMARY (P-Channel)		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DSON</sub> (mΩ) Max
-30V	-4.7A	56 @ V <sub>GS</sub> =-10V
		90 @ V <sub>GS</sub> =-4.5V



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Units
V <sub>DS</sub>	Drain-Source Voltage	30	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub>	Drain Current-Continuous <sup>a</sup>	T <sub>A</sub> =25°C	5.3	A
		T <sub>A</sub> =70°C	4.2	A
I <sub>DM</sub>	-Pulsed <sup>b</sup>	19	-17	A
P <sub>D</sub>	Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	2.0	W
		T <sub>A</sub> =70°C	1.28	W
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 to 150		°C

### THERMAL CHARACTERISTICS

R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient <sup>a</sup>	62.5	°C/W
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Details are subject to change without notice.

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## N-Channel ELECTRICAL CHARACTERISTICS ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30			V
$I_{DS(on)}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$		1		$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	3	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=5.3A$		38	46	m ohm
		$V_{GS}=4.5V, I_D=4.5A$		48	65	m ohm
$g_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=5.3A$		10		S
<b>DYNAMIC CHARACTERISTICS <sup>c</sup></b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V$ $f=1.0MHz$		310		pF
$C_{oss}$	Output Capacitance			73		pF
$C_{rss}$	Reverse Transfer Capacitance			44		pF
<b>SWITCHING CHARACTERISTICS <sup>c</sup></b>						
$t_{D(on)}$	Turn-On Delay Time	$V_{DD}=15V$ $I_D=1A$ $V_{GS}=10V$ $R_{GEN}=6\text{ ohm}$		7.5		ns
$t_r$	Rise Time			9.5		ns
$t_{D(off)}$	Turn-Off Delay Time			16		ns
$t_f$	Fall Time			13		ns
$Q_g$	Total Gate Charge	$V_{DS}=15V, I_D=5.3A, V_{GS}=10V$		5.3		nC
		$V_{DS}=15V, I_D=5.3A, V_{GS}=4.5V$		2.8		nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=15V, I_D=5.3A,$ $V_{GS}=10V$		0.9		nC
$Q_{gd}$	Gate-Drain Charge			1.2		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current			1		A
$V_{SD}$	Diode Forward Voltage <sup>b</sup>	$V_{GS}=0V, I_s=1A$		0.79	1.2	V

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## P-Channel ELECTRICAL CHARACTERISTICS ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$I_{DSs}$	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.8	-3.0	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-4.7A$		46	56	m ohm
		$V_{GS}=-4.5V, I_D=-3.7A$		68	90	m ohm
$g_{FS}$	Forward Transconductance	$V_{DS}=-5V, I_D=-4.7A$		7.5		S
<b>DYNAMIC CHARACTERISTICS <sup>c</sup></b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V$ $f=1.0MHz$		520		pF
$C_{oss}$	Output Capacitance			125		pF
$C_{rss}$	Reverse Transfer Capacitance			78		pF
<b>SWITCHING CHARACTERISTICS <sup>c</sup></b>						
$t_{D(ON)}$	Turn-On Delay Time	$V_{DD}=-15V$ $I_D=-1A$ $V_{GS}=-10V$ $R_{GEN}=6\text{ ohm}$		7.5		ns
$t_r$	Rise Time			12.4		ns
$t_{D(OFF)}$	Turn-Off Delay Time			62		ns
$t_f$	Fall Time			37		ns
$Q_g$	Total Gate Charge	$V_{DS}=-15V, I_D=-4.7A, V_{GS}=-10V$		10.3		nC
		$V_{DS}=-15V, I_D=-4.7A, V_{GS}=-4.5V$		5.2		nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=-15V, I_D=-4.7A,$ $V_{GS}=-10V$		1.1		nC
$Q_{gd}$	Gate-Drain Charge			2.8		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current				-1	A
$V_{SD}$	Diode Forward Voltage <sup>b</sup>	$V_{GS}=0V, I_s=-1A$		-0.77	-1.2	V
<b>Notes</b>						
a. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$ . b. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$ . c. Guaranteed by design, not subject to production testing.						

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## N-Channel

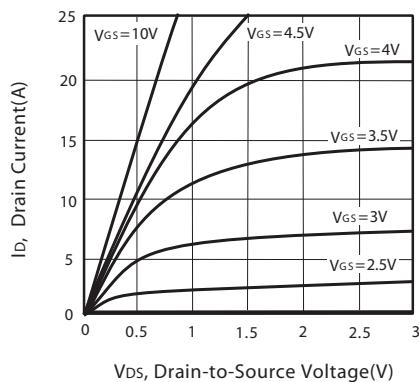


Figure 1. Output Characteristics

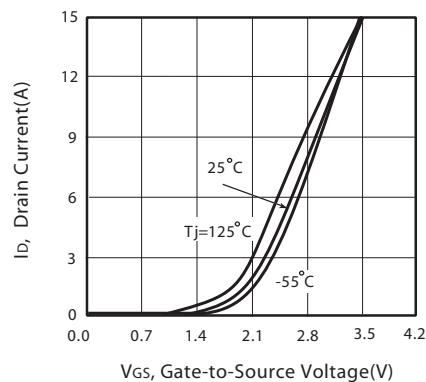


Figure 2. Transfer Characteristics

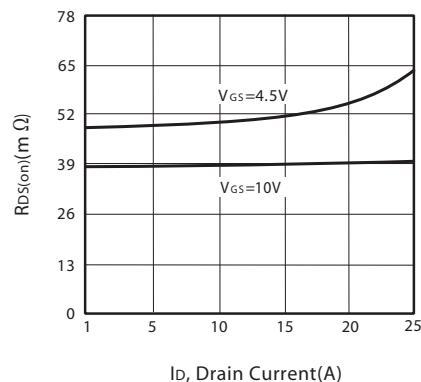


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

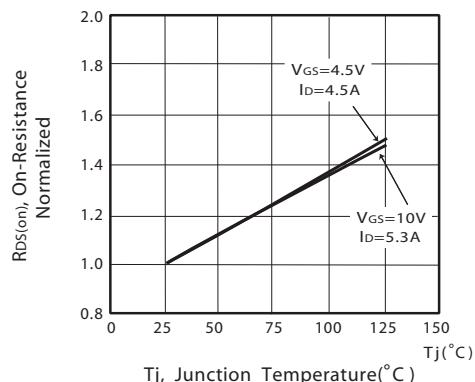


Figure 4. On-Resistance Variation with Drain Current and Temperature

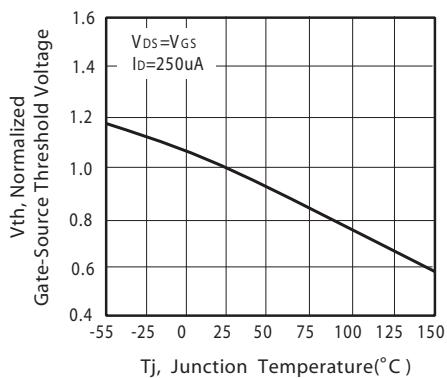


Figure 5. Gate Threshold Variation with Temperature

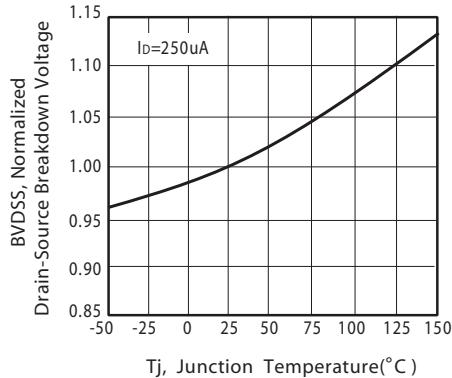


Figure 6. Breakdown Voltage Variation with Temperature

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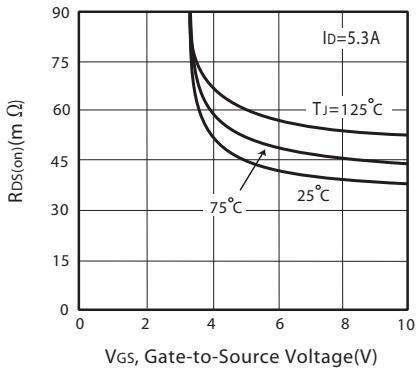


Figure 7. On-Resistance vs.  
Gate-Source Voltage

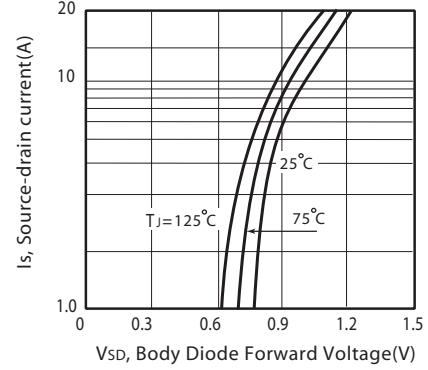


Figure 8. Body Diode Forward Voltage  
Variation with Source Current

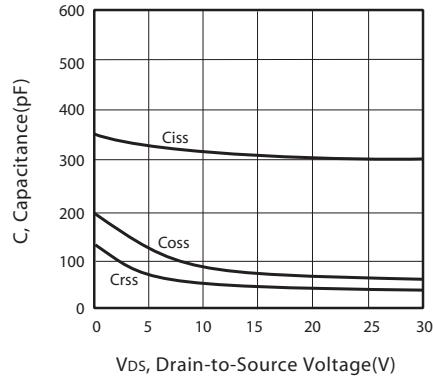


Figure 9. Capacitance

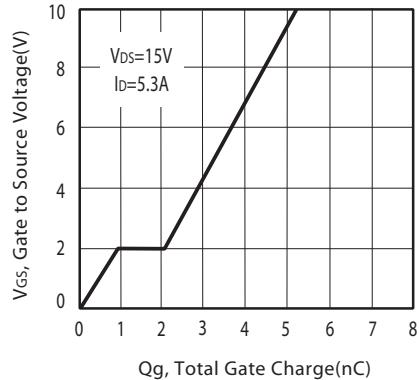


Figure 10. Gate Charge

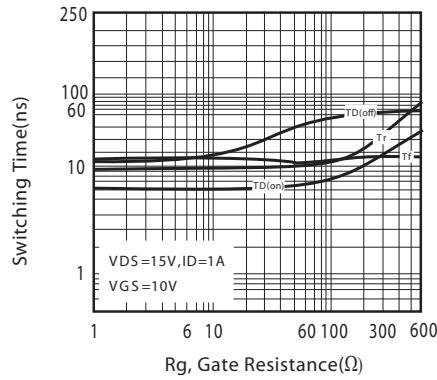


Figure 11. switching characteristics

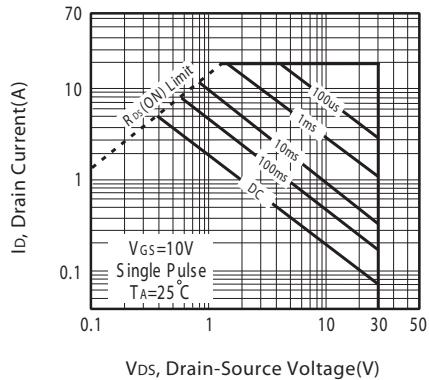
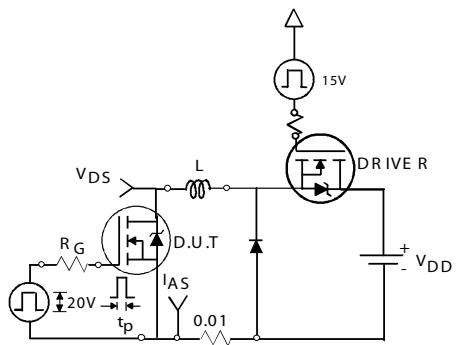


Figure 12. Maximum Safe Operating Area

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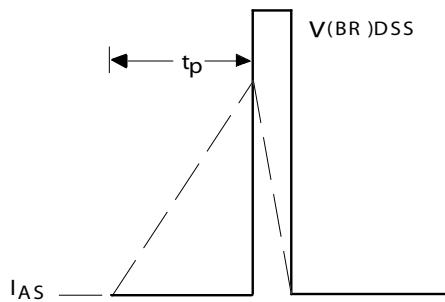
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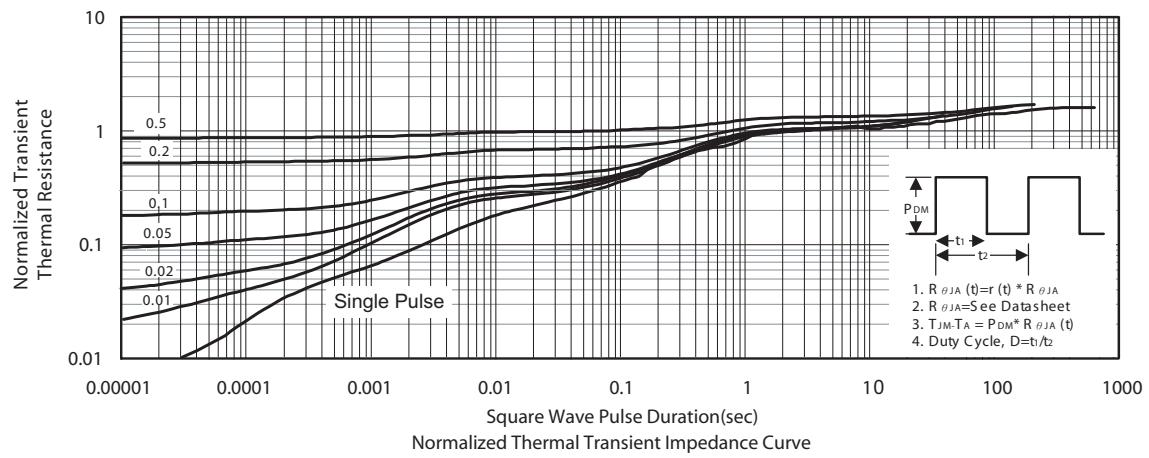
Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.



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## P-Channel

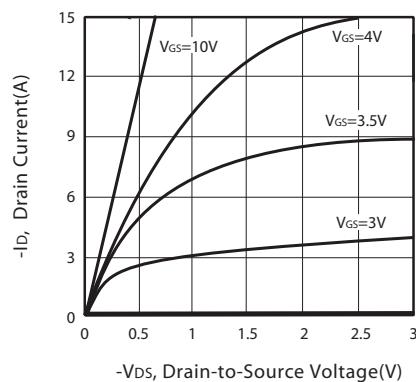


Figure 1. Output Characteristics

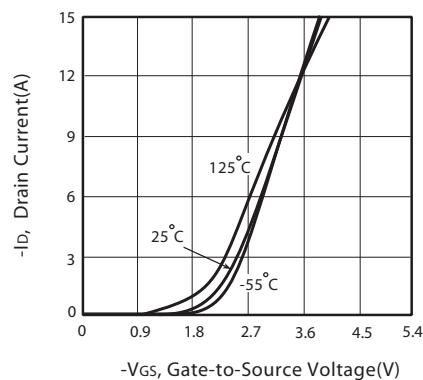


Figure 2. Transfer Characteristics

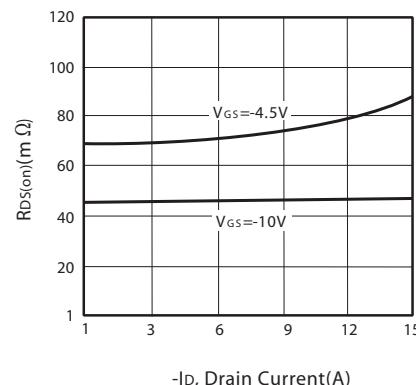


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

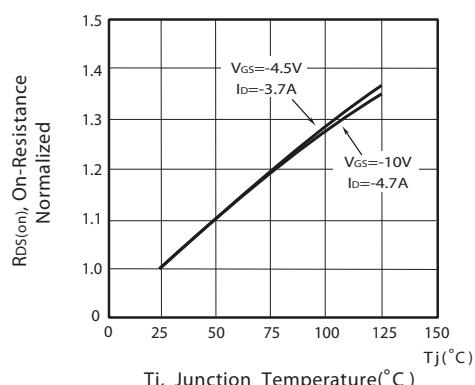


Figure 4. On-Resistance Variation with Drain Current and Temperature

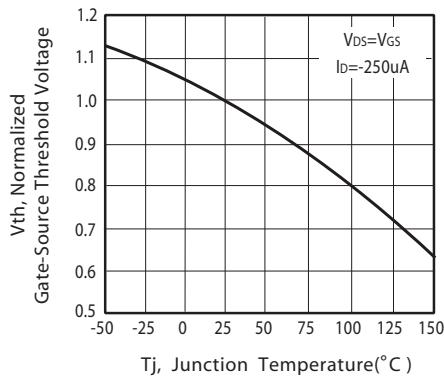


Figure 5. Gate Threshold Variation with Temperature

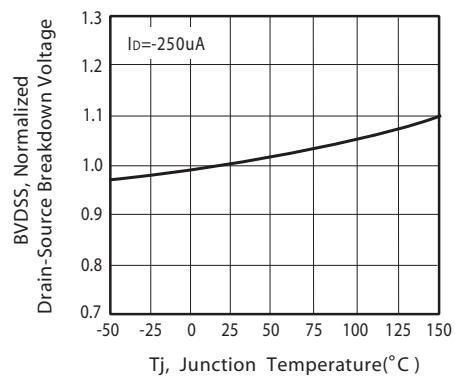


Figure 6. Breakdown Voltage Variation with Temperature

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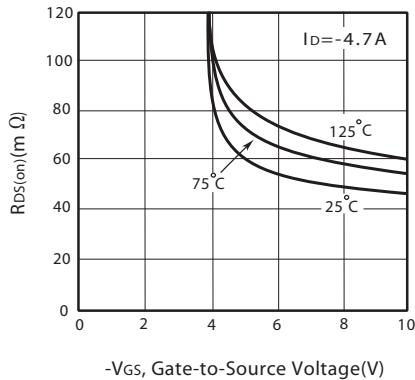


Figure 7. On-Resistance vs.  
Gate-Source Voltage

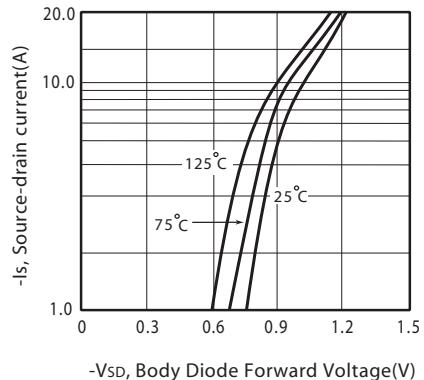


Figure 8. Body Diode Forward Voltage  
Variation with Source Current

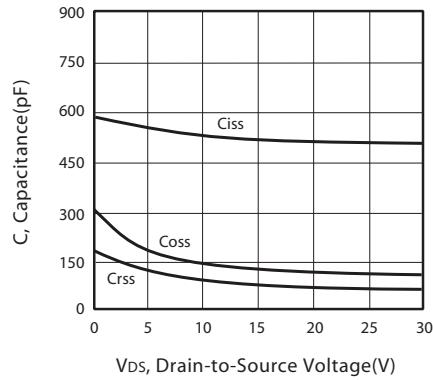


Figure 9. Capacitance

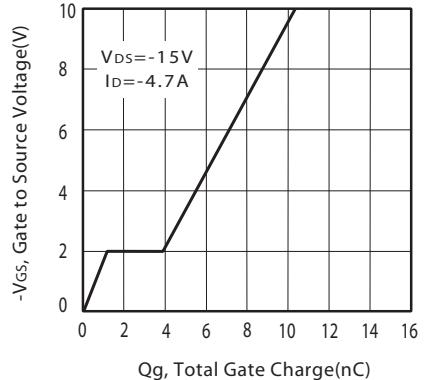


Figure 10. Gate Charge

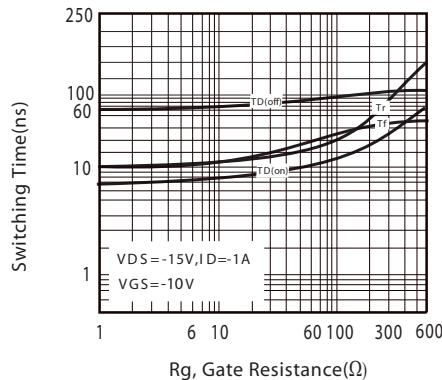


Figure 11. switching characteristics

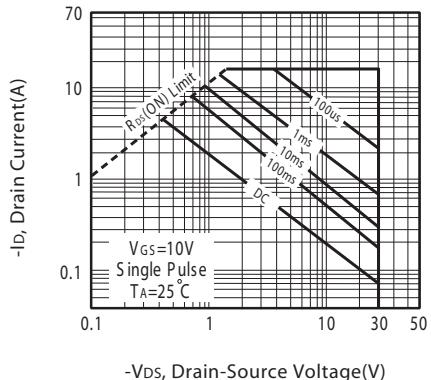
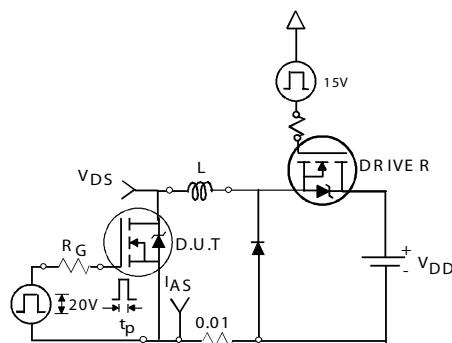


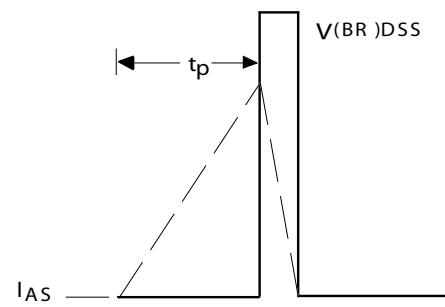
Figure 12. Maximum Safe Operating Area

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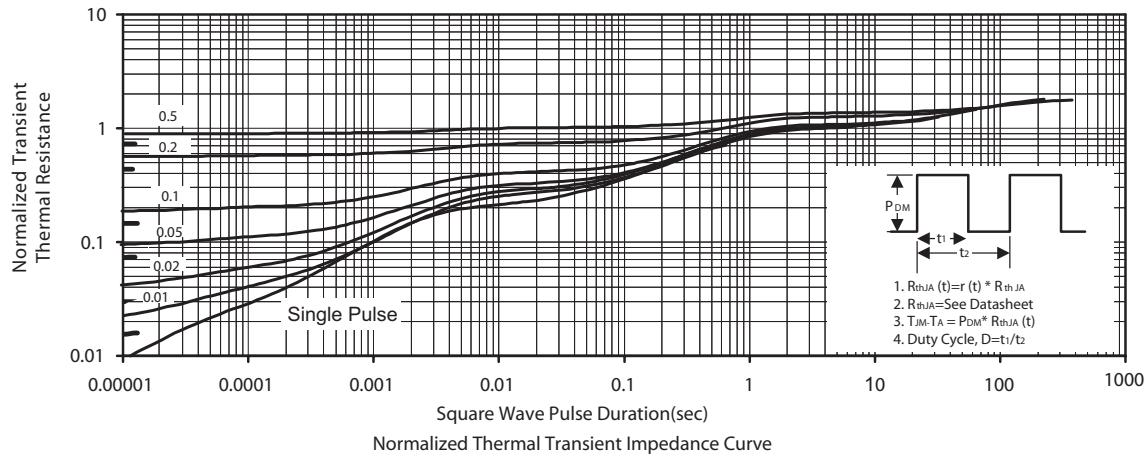
Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.



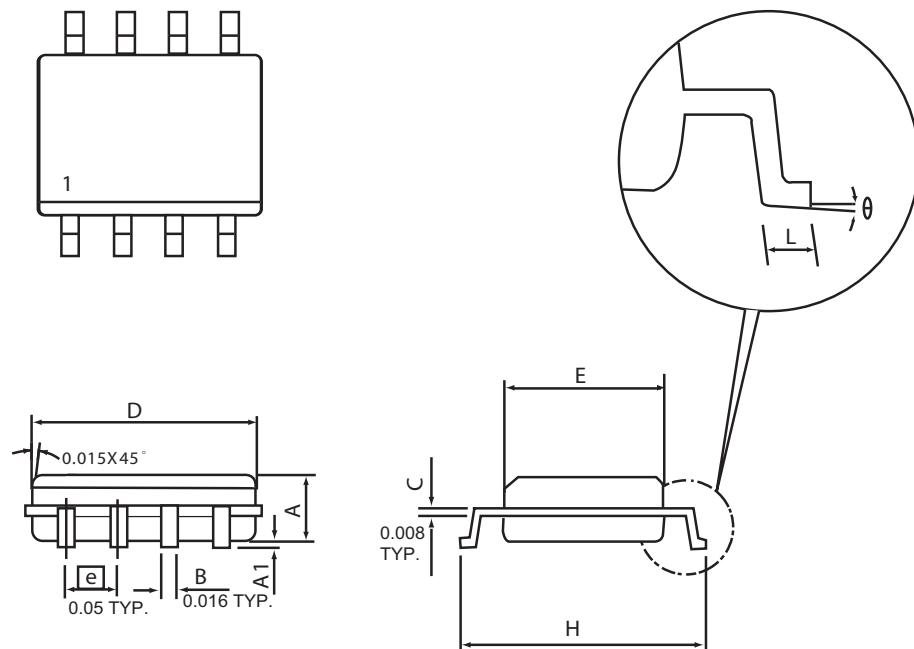
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## PACKAGE OUTLINE DIMENSIONS

SO-8

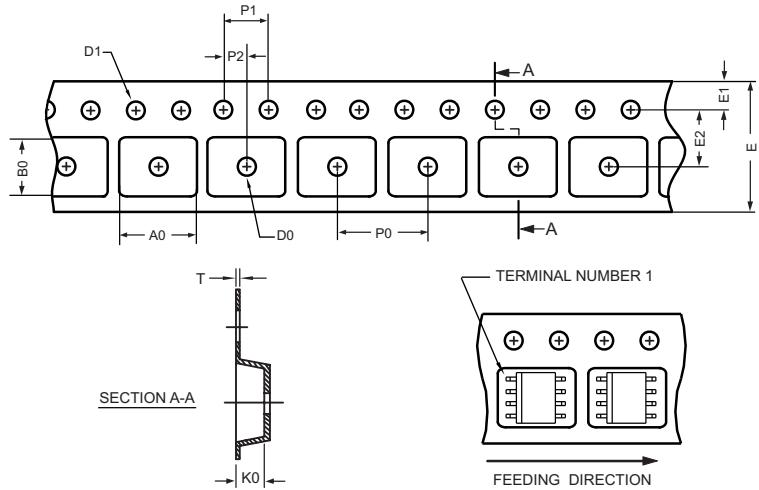


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	4.98	0.189	0.196
E	3.81	3.99	0.150	0.157
H	5.79	6.20	0.228	0.244
L	0.41	1.27	0.016	0.050
$\theta$	$0^\circ$	$8^\circ$	$0^\circ$	$8^\circ$

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## SO-8 Tape and Reel Data

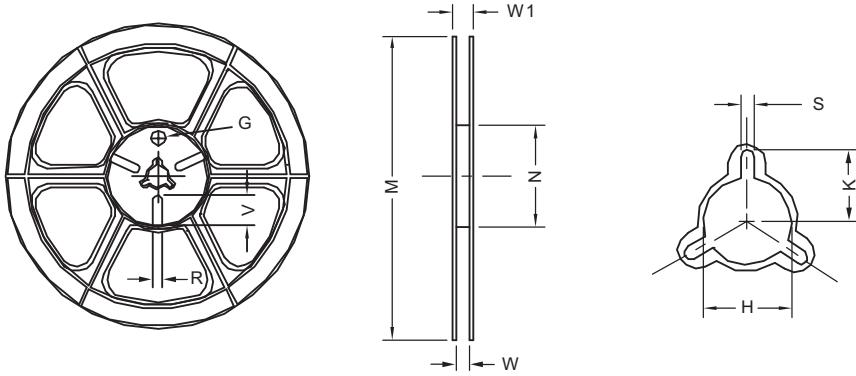
### SO-8 Carrier Tape



unit:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOP 8N 150mil	6.50 $\pm 0.15$	5.25 $\pm 0.10$	2.10 $\pm 0.10$	$\phi 1.5$ (MIN)	$\phi 1.55$ $\pm 0.10$	12.0 $+0.3$ $-0.1$	1.75 $\pm 0.10$	5.5 $\pm 0.10$	8.0 $\pm 0.10$	4.0 $\pm 0.10$	2.0 $\pm 0.10$	0.30 $\pm 0.013$

### SO-8 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	$\phi 330$	$330 \pm 1$	$62 \pm 1.5$	$12.4 + 0.2$	$16.8 - 0.4$	$\phi 12.75 + 0.15$	---	$2.0 \pm 0.15$	---	---	---